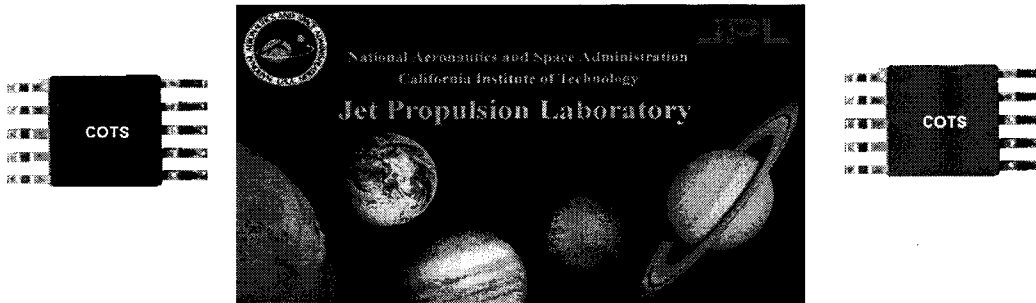


# **Commercialization Of Military And Space Electronics**

**3RD Annual 1999 International Workshop**

## **Commercial Off-The-Shelf (COTS) Program Issues and Results of Upscreening COTS Parts for NASA Flight Hardware**



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### **AGENDA:**

INTRODUCTION OF COTS  
MARS01 PROGRAM/REQUIREMENTS  
MARS01 COTS SCREENING FLOW  
TEST RESULTS - ELECTRICAL, C-SAM, BURN-IN  
VALUE ADDED ANALYSIS (Risk Reduction)  
VALUE ADDED ANALYSIS (Cost)  
IMPACT of COTS++ SCREENING  
SUMMARY



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## **Advocacy for Using COTS(plastic packages):**

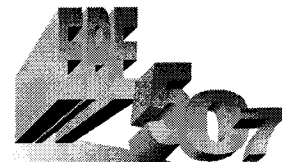
1. More availability of COTS as state of-the-art
2. COTS plastic parts performance capabilities continue to increase  
(e.g. processing power & high density memories)
3. COTS plastic parts enable reduction of hardware weight and volume
4. COTS plastic parts acquisition cost much less than ceramic
5. COTS plastic parts have been reported to demonstrate  
good to excellent reliability in commercial and aerospace applications
6. Often they are the only option when Grade 1 is not offered or available



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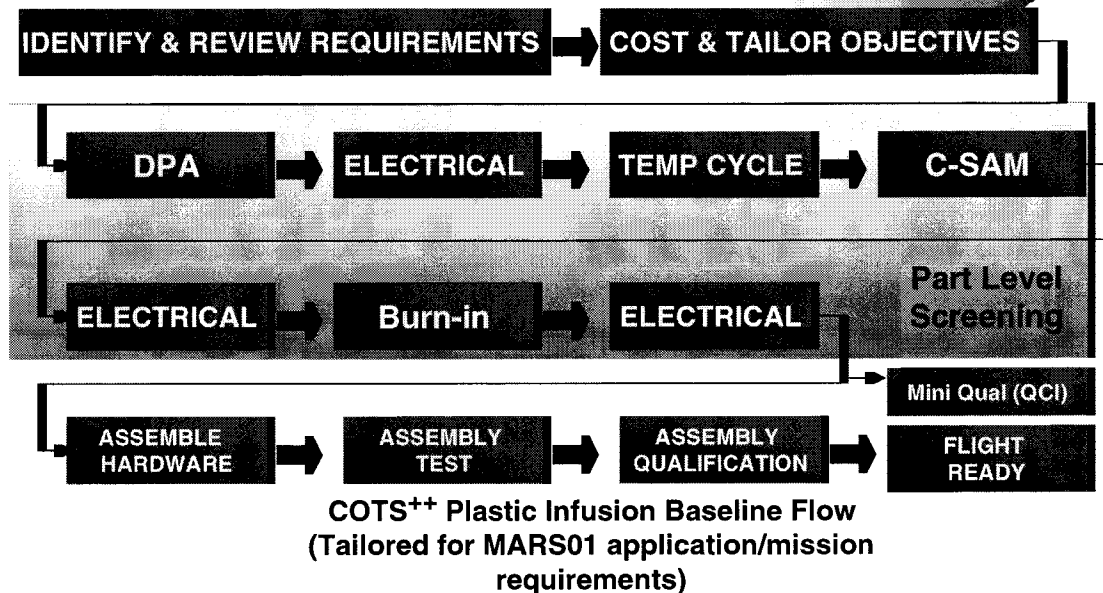
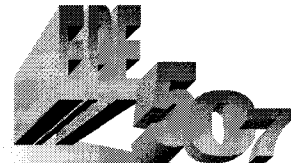
## **COTS PEM Risk Mitigation Addresses the Following Concerns:**

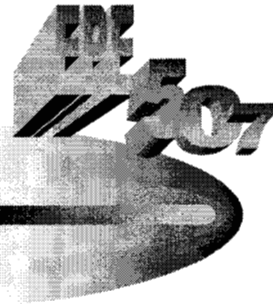
- Narrow Temperature Range for Commercial Grade
- Plastic Assembly Quality
- Lot Non-Uniformity & Traceability
- Adequacy of Vendors Testing
- Infant Mortality
- Die Construction and Quality



## MARS01 Pancam Plastic Parts Reliability Requirements:

- Mission Life  $\geq 1$  years (1500 hours operating)
- Operating Temperature (day only) =  $-50^{\circ}\text{C}$  to  $+10^{\circ}\text{C}$
- Number of T/C  $\approx 365$
- No Assembly Board Burn-In Planned
- Outgassing is a concern
- Environmental Moisture is not critical





## DPA Results:

<u>Amplifier - Vendor A</u>	<u>ADC - Vendor B</u>	<u>DC-DC Converter - Vendor C</u>
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External Visual: Pass	External Visual: Pass	External Visual: Pass
Radiographic: Pass	Radiographic: Pass	Radiographic: Pass
Internal Visual: Pass	Internal Visual: Pass	Internal Visual: Pass
SEM: Pass (4/4)	SEM: Pass <sup>(1)</sup> (7/8)	SEM: Pass (4/4)

(1) Voids found in the sidewall metalization at contact windows and was observed to be thin for one part.  
Although all parts were of the same date code, the dice were clearly from different processing lots.

Note: Reject criteria was defined by JPL to be a potential risk to mission success.



## Initial Electrical Test Results (Pre T/C & C-SAM - No. of Rejects)

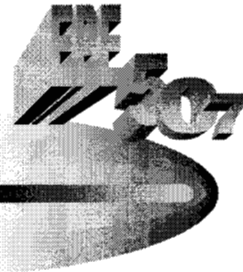
<u>Amplifier - Vendor A</u>	<u>ADC - Vendor B</u>	<u>DC-DC Converter - Vendor C</u>
-----------------------------	-----------------------	-----------------------------------

At +25°C: 0/78	At +25°C: Not tested	At +25°C: 0/78
At -55°C: 0/78	At -55°C: Not tested	At -55°C: 1/78 <sup>(1)</sup>

(1) Failed parametric

Note: T/C precondition = -60C to +25C (10 cycles)

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**C-SAM Results (No. of Rejects):**

**Amplifier - Vendor A**

Top Side: 0/78<sup>(1)</sup>

Back Side: 3/78

Typical Rejects:



Pass <sup>(1)</sup>



Fail

**ADC - Vendor B**

Top Side: 30/78

Back Side: 8/78



Fail



Fail

**DC-DC Converter - Vendor C**

Top Side: 0/78

Thru Scan: 16/78



Fail

Note: Units with delamination are defective and were defined by JPL to be a potential risk to mission success. (1) All units showed 100% delamination caused by a special die top coating. These parts were not rejected. F.A. confirmed a die top coating. This was validated by the supplier.

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**Electrical Test Results (Pre Burn-In - No. of Rejects):**

**Amplifier - Vendor A**

At +25°C: 0

At +55°C: 0

**ADC - Vendor B**

At +25°C: 10 <sup>(1)</sup>

At +55°C: 0

**DC-DC Converter - Vendor C**

At +25°C: 2<sup>(1)</sup>

At +55°C: 1<sup>(1)</sup>

(1) Failures included parametric and functional



**Electrical Test Results (Post Burn-In - No. of Rejects):**

<u>Amplifier - Vendor A</u>	<u>ADC - Vendor B</u>	<u>DC-DC Converter - Vendor C</u>
At +25°C: 0	At +25°C: 0	At +25°C: 0
At -55°C: 0	At -55°C: 3 <sup>(1)</sup>	At -55°C: 0

(1) Failures were parametric and functional

Note: Burn-In Conditions = Dynamic at 72 hrs, @+55C, @max rated Vdd. This condition was calculated to simulate 1500 hrs at -10C using a T acceleration factor of 21 & Ea=.33ev. The 3 burn-in circuits simulated the actual operation of the parts.



**Electrical Test Results (QCI - No. of Rejects):**

<u>Amplifier - Vendor A</u>	<u>ADC - Vendor B</u>	<u>DC-DC Converter - Vendor C</u>
At +25°C: 0	At +25°C: 0	At +25°C: 0
At -55°C: 0	At -55°C: 0	At -55°C: 0

Note: All parts passed (ss = 10 good parts/part type)

Note: Burn-In Conditions = Extended dynamic at 72 hrs, @+55C, @max rated Vdd. This condition was calculated to simulate additional 1500 hrs at -10C using a T acceleration factor of 21 & Ea=.33ev. The 3 burn-in circuits simulated the actual operation of the parts.



## Circuit Card Assembly (CCA) Risk Reduction:

### Amplifier - Vendor A    ADC - Vendor B    DC-DC Converter - Vendor C

Unit yield: 75/78

Unit yield: 31/78

Unit yield: 61/78

#### W.C.Failure Rate Expected Before Screen (COTS):

$$= 1 - [75/78^{11} \times 31/78^{11} \times 61/78^{11} \times 100/100^{11} \times \dots] \leq 70\%$$

#### W.C.Failure Rate Expected After JPL Screen ( COTS<sup>++</sup> ):

$$= 1 - [.990^{11} \times .985^{11} \times .950^{11} \times 100/100^{11} \dots] \leq 8\%$$

Potential Risk of failure has been reduced by  $\approx 62\%$

Note: Vendor B product is potentially more at risk because of high number of pre and post BI rejects as well as the number of package related defects. Rejects and defects were rated as equal risk.



## VALUE ADDED ANALYSIS (Cost):

	<u>Amplifier - Vendor A</u>	<u>ADC - Vendor B</u>	<u>DC-DC Converter - Vendor C</u>
Part Acquisition Cost:	\$ .260k	\$1.8k	\$ .350k
Part Screening Cost:	\$6.8k	\$13.8k	\$6.3k
Engineering O/H Cost:	\$2.0k	\$2.5k	\$2.0k
Value added for screening/CCA:	\$8.8k/9 + \$16.3k/9 + \$8.3k/9 = \$3.7k		
Risk of Failure Cost Before Screen/CCA:	\$30k(all material & labor) x 9 x .70 f.r. = \$189k		
Risk of Failure Cost with Screen/CCA:	(\$30k + \$33.4k) x 9 x .08 f.r. = \$45.6k (>400% Potential Savings)		



### COTS++ PEM Screen Impact on Risk Mitigation:

	<u>Amplifier</u>	<u>ADC</u>	<u>DC-DC Converter</u>
• Narrow Temperature Range for Commercial Grade	1	1	3
• Plastic Assembly Quality	3	9	9
• Lot Non- Uniformity & Traceability	1	9	3
• Adequacy of Vendors Testing	1	9	3
• Infant Mortality	1	9	1
• Die Construction and Quality	1	1	1
Total	8	38	20

Risk mitigation weighting factors used: Minimum = 1, Moderate = 3, Significant = 9



### Summary/Conclusions:

- The concerns/risks anticipated with using COTS PEMS have been validated from the results of the tailored screening flow used.
- The tailored screening flow used has significantly reduced the potential risk of failure for the MARs01 CCA by approximately 60%.
- The cost of failure for future CCAs manufactured with the screened parts has been reduced by as much as 400% (before launch).
- Using COTS PEMs without any value added screening/characterization will jeopardize any Project until the unknown risks/concerns are understood and mitigated.



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## **Reported Failure Mechanisms from PEM Delamination:**

- Stress-induced massivation damage over the die surface
- Wire bond degradation due to shear displacement
- Accelerated metal corrosion
- Die attach adhesion
- Intermittent electricals at high temperature
- Popcorn cracking
- Die cracking

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**11/07**

**Summary/Conclusions:**

**CHTS++ Upstreaming Results**

